

Matt Tin SAT 20 1 电镀锡

高市占率有机酸电镀锡系统

Strong market share of organic acid base tin plating tech

Matt Tin SAT 20 1 是一款已深耕市场多年的电镀锡化学添加剂，广受客户信赖并在有机酸锡市场中占据领先地位。其独特的锡晶格结构与卓越的保护能力，使其在高层数厚板 PCB 制程中具有显著优势，有效防止通孔内电镀铜受到蚀刻液攻击。

Matt Tin SAT 20 1 has been well-established in the market for many years and is widely trusted by customers. It holds a leading position in the organic acid tin market. Its unique grain structure and excellent protective capabilities provide advantages to the HLC PCB process, effectively preventing the electroplated copper inside the TH from being attacked by etching solutions.

锡晶格组织细致，即使在较低锡厚下也能在高低电流区域均匀保护底部的电镀铜，提供全面保护。

The fine and uniform Tin grain structure provides protection for the electroplated copper beneath, even at lower tin thickness, from high to low ASD areas to ensure good protection for the hull area.

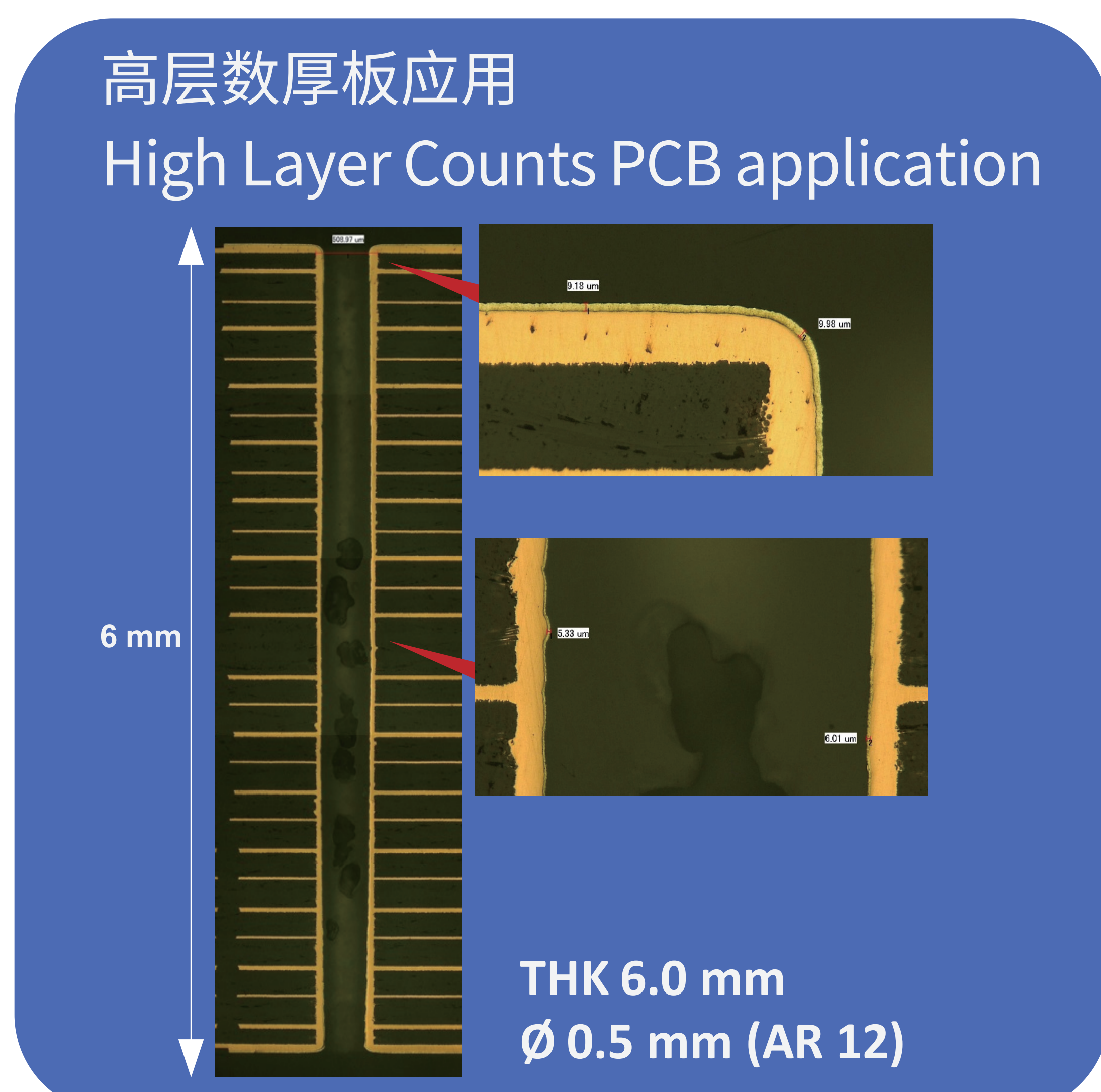
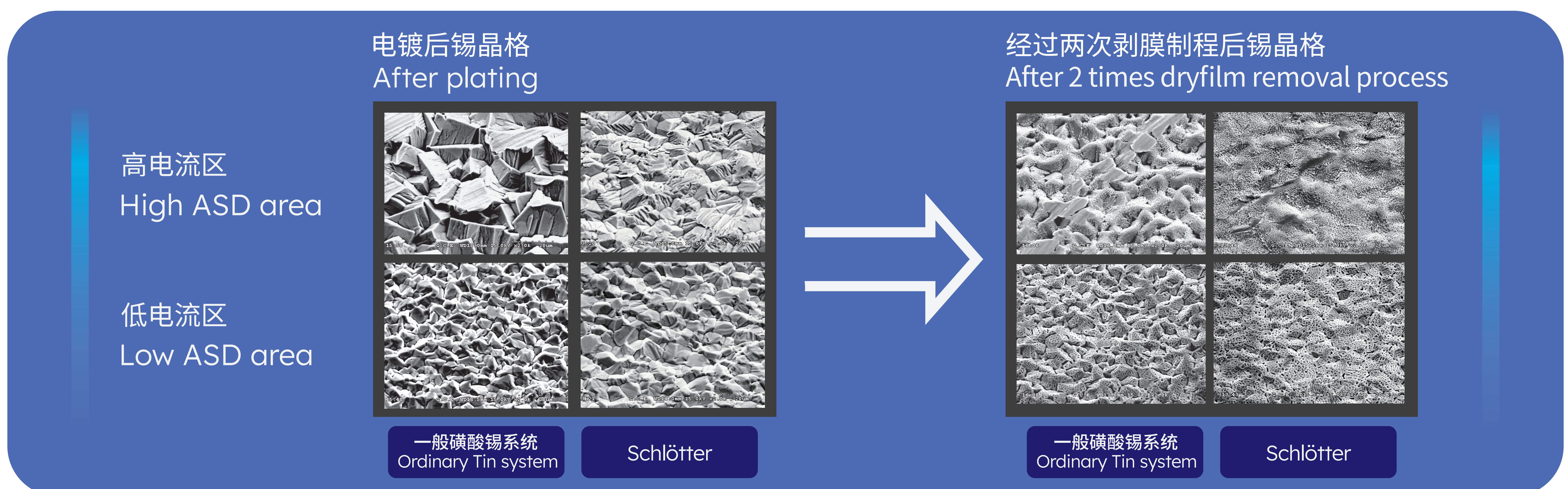
适用于高层数厚板 PCB，Matt Tin SAT 20 1 可在电镀锡层下有效保护通孔中的电镀铜，避免蚀刻液对铜层的侵蚀。

Matt Tin SAT 20 1 effectively protects the electroplated copper within TH under the tin plating layer which is suitable for HLC PCB, preventing etching solutions attack from the copper layer

产品优势 Benefits

细致紧密的晶格组织 - 细致且均匀的锡晶格组织，经过多次剥膜程序高低电流区域的锡晶格依旧提供出色的保护能力。

Fine crystal structure - Fine and uniform tin grain structure can provide outstanding protection in every current density area after multi-dryfilm removal process.



CO₂ 足迹 CO₂ Footprint

